

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	15	((semiconduct\$3 or wafer or silicon or "Si").ti,ab. and (resist or photoresist) same solder\$3 near3 (ball\$3 or bump\$3) same (heat\$3 or thermal\$3 or temperature or degree) and (benzocyclobutene or benzo adj cyclobutene or benzocyclo adj butene or BCB) same (resist or photoresist))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/06/29 11:57
L3	1	(solder\$3 near3 (ball\$3 or bump\$3) same (heat\$3 or thermal\$3 or temperature or degree) same (benzocyclobutene or benzo adj cyclobutene or benzocyclo adj butene or benzo adj cyclo adj butene or BCB) same (resist or photoresist)) not L2	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/06/29 11:57
L4	35	(solder\$3 near3 (ball\$3 or bump\$3) same (heat\$3 or thermal\$3 or temperature or degree) and ((benzocyclobutene or benzo adj cyclobutene or benzocyclo adj butene or benzo adj cyclo adj butene or BCB) same (resist or photoresist)) not L2 not L3	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/06/29 11:57
L5	8969	(430/311,313-314,316-319, 329-330).ccls.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	ON	2005/06/29 11:57
L6	10543	(438/108,115,612-615,660,694).ccls.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	ON	2005/06/29 11:57
L7	1434	(228/164,203,232,246,262.9).ccls.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	ON	2005/06/29 11:57
L8	20824	L5 or L6 or L7 not L2 not L3 not L4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	ON	2005/06/29 11:57

L9	184	L8 and ((resist or photoresist or polyimide or benzocyclobutene or benzo adj cyclobutene or benzocyclo adj butene or benzo adj cyclo adj butene or BCB) same (transition adj temperature or "Tg" or "T.sub.g" or degrees) and (solder same (melt\$3 or heat\$3 or temperature or degrees or reflow\$3))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/06/29 11:57
L10	2	((semiconductor or wafer) and (resist or photoresist) and solder\$3 and reflow\$3 and passivat\$3 and (UBM or under bump metal\$8) and (transition temperature or "Tg" or "T.sub.g")).clm:	US-PGPUB	ADJ	ON	2005/06/29 11:57
L11	1	("6782897").PN.	US-PGPUB; USPAT	OR	OFF	2005/06/29 11:57
L12	56	(Chao Yuan near2 Su or Chia Fu near2 Lin or Hsin Hui near2 Lee or Yen Ming near2 Chen or Kai Ming near2 Ching or Li Chih near2 Chen).in. not L2 not L3 not L4 not L9 not L10 not L11	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	ON	2005/06/29 11:57
L14	1478	430/312.ccls. not L2 not L3 not L4 not L9 not L10 not L12	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	ON	2005/06/29 11:58
L15	4	14 and ((resist or photoresist or polyimide or benzocyclobutene or benzo adj cyclobutene or benzocyclo adj butene or benzo adj cyclo adj butene or BCB) same (transition adj temperature or "Tg" or "T.sub.g" or degrees) and (solder same (melt\$3 or heat\$3 or temperature or degrees or reflow\$3))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/06/29 11:59